1. Package summary

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<td>1.35</td>
<td>mm</td>
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<td>actual quantity of termination</td>
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<td>-</td>
<td>5</td>
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Table 1. Package summary
2. Package outline

Fig. 1. Package outline TSSOP5 (SOT353)
3. Soldering

Fig. 2. Reflow soldering footprint for TSSOP5 (SOT353)

Fig. 3. Wave soldering footprint for TSSOP5 (SOT353)
4. Legal information

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